

Trident 1 Remote Probing Station Option

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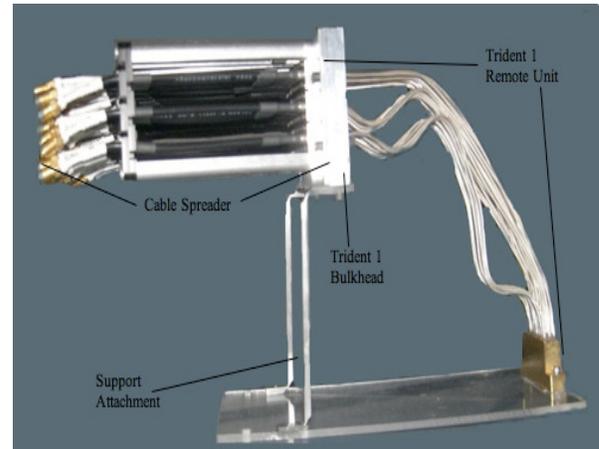
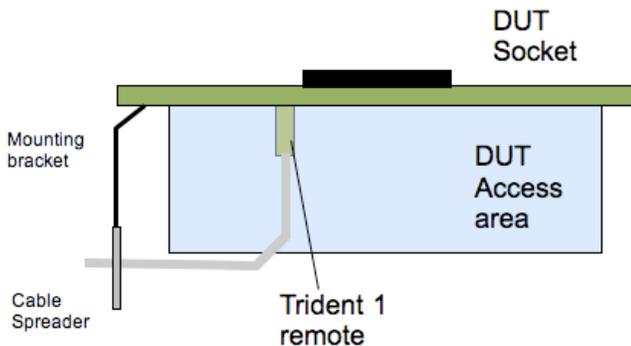


Product Description

The Trident 1 remote probe option is the same 36 channel high bandwidth signal probing system modified to bring instrument cabling to difficult to reach ATE and Lab board set ups. This is a semi custom option to the T1 system and is used when the probes must traverse device cooling or ATE electronic housings. It delivers the same density high edge rate, high bit rate signal bundle to instrumentation with low loss, flat response and the high level of signal integrity required for demanding test and characterization applications.

Features of the T1 Remote Probing System

- ◆ Tight channel skew.
- ◆ Top or Bottom mount board attachment
- ◆ Fits SMP to SMA Cable Spreader
- ◆ Adaptable Angles
- ◆ Minimizes path to DUT
- ◆ Allows for Automatic Handling Equipment



Trident 1 Remote Probe System Setup

Shown here is the Trident 1, and cable spreader used to access signals from underneath the device through and access area on the bottom of the DUT board.

Operational Block Diagram

Remote probing solutions and the ability to customize the high density wave guide angles of the probe system, minimizes the distance from the probe to the socket,contact, enabling the test array on the device to be located through a minimal trace length. This can make a big difference in performance and measurement stability, when compared to a signal mounted through 6-12 inches of boards trace.

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This design also keeps the top of the board clean for thermal control and for using automatic handling equipment for the DUT. This can be used with FA equipment to send high speed stimulus to the SERDES for IR and EMI probing and de-capped device debug.